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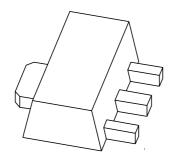
If you have any questions related to the data sheet, please contact our nearest sales office via e-mail or telephone (details via **salesaddresses@nexperia.com**). Thank you for your cooperation and understanding,

Kind regards,

Team Nexperia

DISCRETE SEMICONDUCTORS

DATA SHEET



PXT4403 PNP switching transistor

Product data sheet Supersedes data of 1999 Apr 14 2004 Nov 22



PNP switching transistor

PXT4403

FEATURES

- High current (max. 600 mA)
- Low voltage (max. 40 V).

APPLICATIONS

• Switching and linear amplification.

DESCRIPTION

PNP switching transistor in a SOT89 plastic package. NPN complement: PXT4401.

MARKING

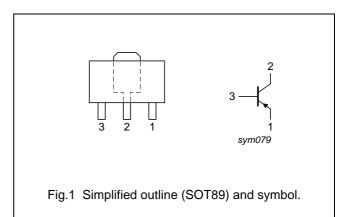
TYPE NUMBER	MARKING CODE(1)
PXT4403	*2T

Note

- 1. * = p: Made in Hong Kong.
 - * = t: Made in Malaysia.
 - * = W: Made in China.

PINNING

PIN	DESCRIPTION
1	emitter
2	collector
3	base



ORDERING INFORMATION

TYPE NUMBER	PACKAGE			
TIPE NOWIBER	NAME DESCRIPTION VEF			
PXT4403	SC-62	plastic surface mounted package; collector pad for good heat transfer; 3 leads	SOT89	

PNP switching transistor

PXT4403

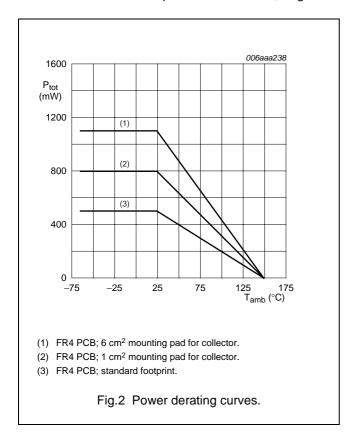
LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 60134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V _{CBO}	collector-base voltage	open emitter	_	-40	V
V _{CEO}	collector-emitter voltage	open base	_	-40	V
V _{EBO}	emitter-base voltage	open collector	_	-5	V
I _C	collector current (DC)		_	-600	mA
I _{CM}	peak collector current		-	-800	mA
I _{BM}	peak base current		_	-200	mA
P _{tot}	total power dissipation	T _{amb} ≤ 25 °C			
		note 1	_	0.5	W
		note 2	_	0.8	W
		note 3	_	1.1	W
T _{stg}	storage temperature		-65	+150	°C
Tj	junction temperature		_	150	°C
T _{amb}	ambient temperature		-65	+150	°C

Notes

- 1. Device mounted on a printed-circuit board, single-sided copper, tin-plated and standard footprint.
- 2. Device mounted on a printed-circuit board, single-sided copper, tin-plated and mounting pad for collector 1 cm².
- 3. Device mounted on a printed-circuit board, single-sided copper, tin-plated and mounting pad for collector 6 cm².



PNP switching transistor

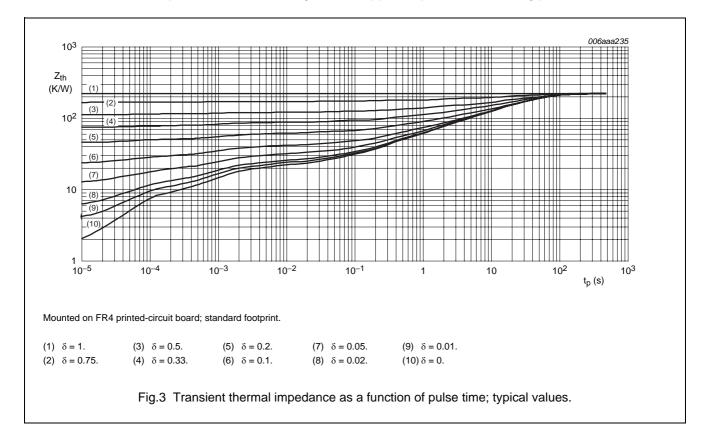
PXT4403

THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT
R _{th(j-a)}	thermal resistance from junction to	in free air		
	ambient	note 1	250	K/W
		note 2	156	K/W
		note 3	113	K/W
R _{th(j-s)}	thermal resistance from junction to soldering point		30	K/W

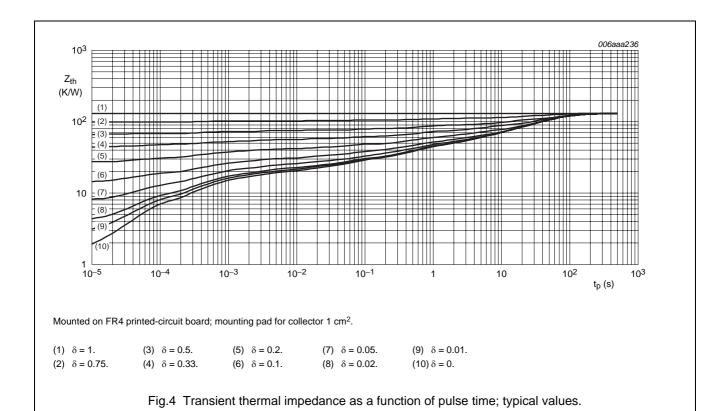
Notes

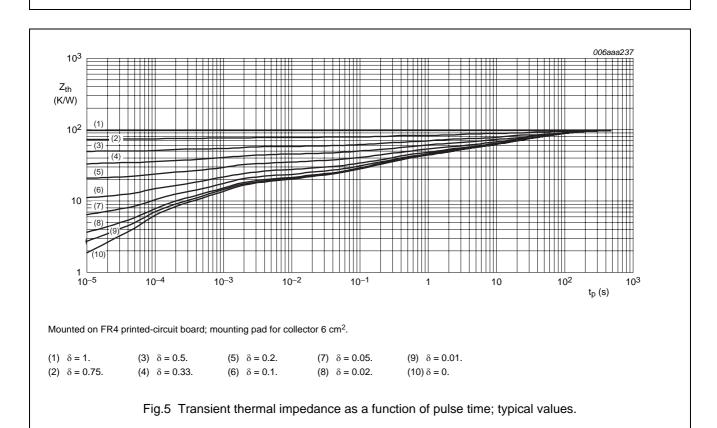
- 1. Device mounted on a printed-circuit board, single-sided copper, tin-plated and standard footprint.
- 2. Device mounted on a printed-circuit board, single-sided copper, tin-plated and mounting pad for collector 1 cm².
- 3. Device mounted on a printed-circuit board, single-sided copper, tin-plated and mounting pad for collector 6 cm².



PNP switching transistor

PXT4403





PNP switching transistor

PXT4403

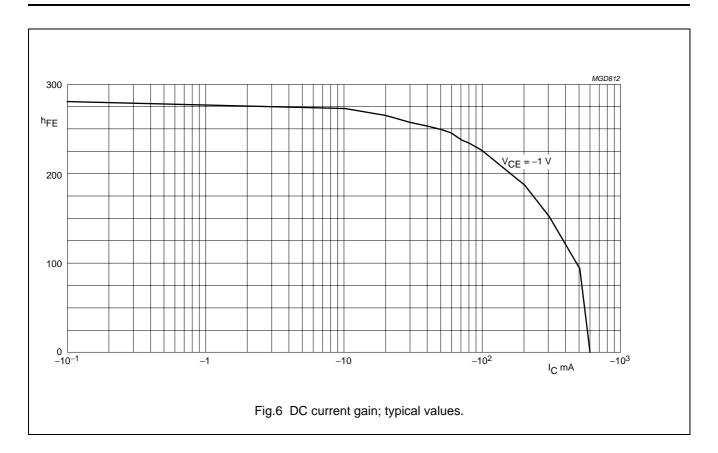
CHARACTERISTICS

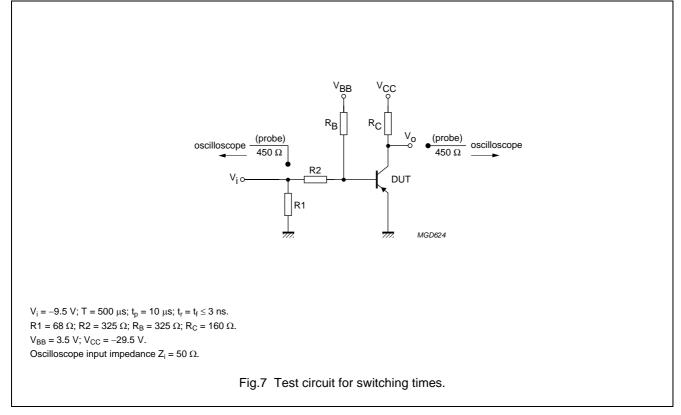
 T_{amb} = 25 °C unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
I _{CBO}	collector-base cut-off current	I _E = 0 A; V _{CB} = -40 V	_	-50	nA
I _{EBO}	emitter-base cut-off current	I _C = 0 A; V _{EB} = -5 V	_	-50	nA
h _{FE}	DC current gain	$I_C = -0.1 \text{ mA}; V_{CE} = -1 \text{ V}$	30	_	
		$I_C = -1 \text{ mA}; V_{CE} = -1 \text{ V}$	60	-	
		$I_C = -10 \text{ mA}; V_{CE} = -1 \text{ V}$	100	-	
		$I_C = -150 \text{ mA}; V_{CE} = -2 \text{ V}$	100	300	
		$I_C = -500 \text{ mA}; V_{CE} = -2 \text{ V}$	20	-	
V _{CEsat}	collector-emitter saturation	$I_C = -150 \text{ mA}; I_B = -15 \text{ mA}$	_	-400	mV
	voltage	$I_C = -500 \text{ mA}; I_B = -50 \text{ mA}$	_	-750	mV
V _{BEsat}	base-emitter saturation voltage	$I_C = -150 \text{ mA}; I_B = -15 \text{ mA}$	_	-950	mV
		$I_C = -500 \text{ mA}; I_B = -50 \text{ mA}$	_	-1.3	V
C _c	collector capacitance	$I_E = i_e = 0 \text{ A}; V_{CB} = -10 \text{ V}; f = 1 \text{ MHz}$	_	8.5	pF
C _e	emitter capacitance	$I_C = i_c = 0 \text{ A}; V_{EB} = -500 \text{ mV}; f = 1 \text{ MHz}$	_	35	pF
f _T	transition frequency	$I_C = -20 \text{ mA}; V_{CE} = -10 \text{ V}; f = 100 \text{ MHz}$	200	-	MHz
Switching t	Switching times (between 10% and 90% levels); (see Fig.7)				
t _{on}	turn-on time	$I_{Con} = -150 \text{ mA}; I_{Bon} = -15 \text{ mA};$	_	40	ns
t _d	delay time	I _{Boff} = 15 mA	_	15	ns
t _r	rise time		_	30	ns
t _{off}	turn-off time		_	350	ns
t _s	storage time		_	300	ns
t _f	fall time		_	50	ns

PNP switching transistor

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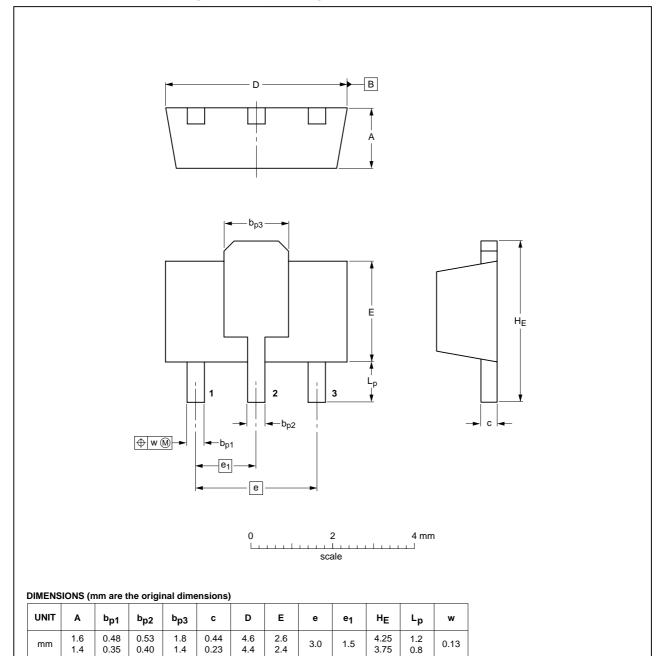
PNP switching transistor

PXT4403

PACKAGE OUTLINE

Plastic surface-mounted package; collector pad for good heat transfer; 3 leads

SOT89



OUTLINE	REFERENCES		EUROPEAN	ISSUE DATE		
VERSION	IEC	JEDEC	JEITA		PROJECTION	ISSUE DATE
SOT89		TO-243	SC-62			-04-08-03 06-03-16

PNP switching transistor

PXT4403

DATA SHEET STATUS

DOCUMENT STATUS ⁽¹⁾	PRODUCT STATUS ⁽²⁾	DEFINITION
Objective data sheet	Development	This document contains data from the objective specification for product development.
Preliminary data sheet	Qualification	This document contains data from the preliminary specification.
Product data sheet	Production	This document contains the product specification.

Notes

- 1. Please consult the most recently issued document before initiating or completing a design.
- 2. The product status of device(s) described in this document may have changed since this document was published and may differ in case of multiple devices. The latest product status information is available on the Internet at URL http://www.nxp.com.

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NXP Semiconductors

Customer notification

This data sheet was changed to reflect the new company name NXP Semiconductors, including new legal definitions and disclaimers. No changes were made to the technical content, except for package outline drawings which were updated to the latest version.

Contact information

For additional information please visit: http://www.nxp.com
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Printed in The Netherlands R75/04/pp10 Date of release: 2004 Nov 22 Document order number: 9397 750 13899

